COMPUCOM GROUP OF COLLEGES
COMPUCOM INSTITUTE OF TECHNOLOGY & MANAGEMENT
CAMPUS PLACEMENT NOTICE

Company Name	**Apstia LLP**
Company website	**https://www.apstia.com/**
Company profile	We are providing a feasibly long term reliable solution for new edge medium & Small enterprises for IT support and maintenance. Apart from IT support we are involved in the cybersecurity of systems since the last decade and evolving our processes and updating tools for everyday cyber threats as well as performance optimization of systems.
Job designation	**Jr. Software Developer**
Job location	Jaipur, rajasthan
No of openings	25
Tentative Date of joining	1st march 2023
Compensation	1. **6-12,000 during probation period (6 month)** 2. **2.00 to 5.00 LPA post probatio(based on performance)**
Job Description/Responsibilities	1. Perform a mix of maintenance, enhancements, and new development as required. 2. Designing and building web applications using Laravel 3. Troubleshooting issues in the implementation and debug builds. 4. Maintaining web-based applications. 5. Testing functionality for users and the backend. 6. Ensuring that integrations run smoothly. 7. Designing database schema 8. Creating application and server architecture 9. Creating development patterns for APIs 10. Architecting development patterns for client-side applications 11. Implementing an elegant, intuitive user experience using latest front-end and back-end technologies 12. Implementing server-side code and designing the data architecture using modern web frameworks 13. You will be responsible for managing the interchange of data between the server and the users. 14. Design and implementation of low-latency, high- availability, and performant applications 15. Be able to analyze performance, security and scalability considerations of design.
Education / Doc required	**BCA, MCA, B.Tech(cs)**
Skill set required	**PHP, MySQL, HTML, CSS, JavaScript, Bootstrap, jQuery(Good to have)**
Selection/Interview process	**Basic development concept test (30 - 60 minutes)** **Technical round of interview**
Offer letter/Letter of Intent	After the document process.
Announcement of Result Same day Yes/No	After the process is complete.
Interview Date and Timing	16/02/2023 (09:00 AM)
Bond	24 month